WAYON Features Typical Vibration Resistance Main Characteristics 10-60Hz at 0.75mm amplitude SMD fuse; Fast Acting(F);2410 60-2000Hz at 10g acceleration Designed to UL E311435 Stock Temperature Materials +10℃ to +60℃ Body: Ceramic Relative humidity:≤75% yearly average End Caps: Copper plated with silver Without dew, maximum 30 days at 95% **Environment Standard** Operating temperature: Lead-free, Halogen-free, RoHS -55°C to +125°C (with de-rating) 2410WNF series SMD chip fuse (Rev:F)Applications Circuit Protecting in notebook PC, telecom system, LCD/PDP TV, wireless goods,LCD monitor, white goods, LCD/PDP panel, game console, power supply, net working and other electronics products. Product Dimensions and Recommended Land Pattern (mm) 1.6+0.58.6 9 e. 3.0 2.6 6.5±0.5 2.8 ± 0.2 **Dimensions Recommended Land Pattern Clear-Time Characteristics (Fast Acting)** % of current rating Clear-time at 25 °C 100% 4 hours min. 200% 5 seconds max. Part Numbering 2410 W NF 200A 125V (A) (1) (2) (3) (4) (5) (6) (1) Size code: Standard EIA Chip Size (2) Company code: Wayon Chip Fuse (3) Series code: NF series (4) Current rating code:200A-2A (5) Voltage rating code:125V-125VDC (6) Supplementary Code: The default is empty, alphabet and number denoting customer code or package code. Specifications are subject to change without notice.

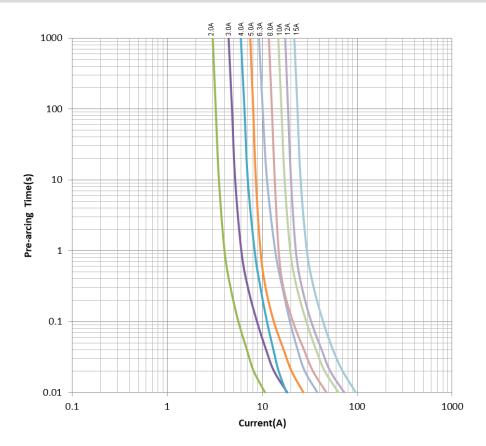
Electrical Characteristics

Part number	Current Rating	Voltage Rating	Interrupting Ratings	Nominal Cold DCR	Nominal I ² t	Marking Code
	A	V	A	mΩ	(A²s)	
2410WNF200A125V	2	125V AC 125V DC	50A or 10In @ 125V AC 300A @ 125V DC	25.2	0.8	2F
2410WNF250A125V	2.5			20	2.06	2F5
2410WNF300A125V	3			17.8	1.95	3F
2410WNF315A125V	3.15			17.81	3	3F1
2410WNF400A125V	4			13.4	4	4F
2410WNF500A125V	5			9.6	7.5	5F
2410WNF630A125V	6.3			7.6	13	6F3
2410WNF700A125V	7			7.3	16	7F
2410WNF800A125V	8			6.35	20	8F
2410WNF1000A125V	10			4.9	35	10F
2410WNF1200A125V	12		50A@125V	4.1	40	12F
2410WNF1500A125V	15		AC/DC	3.3	55	15F

Notice: 1. Permissible continuous operating current is ≤100% at ambient temperature of 23° C (73.4° F) 2. The current values used for calculating I2T should be 10In current.

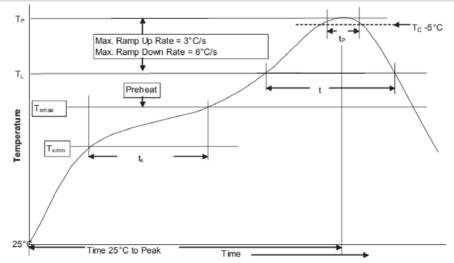
Specifications are subject to change without notice.

Average Clear-Time Curves



Specifications are subject to change without notice.

Solder Reflow Recommendations



Recommended conditions for hand soldering:

1.Infrared Reflow:

Temperature: 260 ℃

Time: 5sec Max.

Recommend reflow profile

2.Wave Soldering Reservoir Temperature: 260°C

Time in Reservoir: 10sec Max.

	Profile Feature	Pb-Free Assembly	
Average	Ramp-UP Rate(Tsmax to Tp)	3℃/s Max.	
	Temperature Min(Ts min)	150 ℃	
Preheat	Temperature Max(Ts max)	200 ℃	
	Time(Tsmin to Ts max)	60sec \sim 120sec	
Liquidous temperature(T _L) Time at liquidous(t _L)		217℃ 60~150s	
Peak pa	ackage body temperature(Tp)	260 ℃	
Time (tP) within 5°C of the specified classification temperature (Tc)		30s	
Average ramp-down rate (Tp to Tsmax)		6℃/s Max.	
Time (25 $^\circ C$ to Peak Temperature)		8 minutes Max.	

Reliability Tests:

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Test	Requirement	Test condition	Test reference
High Temperature	DCR change ≤±10%,Conforming to	85°C,96hours.	Refer to WAYON
Test	Clear-Time characteristics		Standard
Low Temperature	DCR change ≤±10%,Conforming to	-40°C,96hours.	Refer to WAYON
Test	Clear-Time characteristics		Standard
High Humidity Test	DCR change ≤±10%,Conforming to	40°C,95%RH,	Refer to WAYON
	Clear-Time characteristics	96hours.	Standard
Thermal shock	DCR change ≤±10%,Conforming to	-40°C/30min,85°C/30min,	MTL-STD-202
	Clear-Time characteristics	100cycles	Method 107
Falling Shock Test	DCR change ≤±10%	from 75 cm high	Refer to WAYON
	No mechanical damage	natural land on flat plate	Standard
	High Temperature Test Low Temperature Test High Humidity Test Thermal shock	High Temperature TestDCR change ≤±10%,Conforming to Clear-Time characteristicsLow Temperature TestDCR change ≤±10%,Conforming to Clear-Time characteristicsHigh Humidity TestDCR change ≤±10%,Conforming to Clear-Time characteristicsThermal shockDCR change ≤±10%,Conforming to Clear-Time characteristicsFalling Shock TostDCR change ≤±10%	High Temperature TestDCR change $\leq \pm 10\%$, Conforming to Clear-Time characteristics 85° C,96hours.Low Temperature TestDCR change $\leq \pm 10\%$, Conforming to Clear-Time characteristics -40° C,96hours.High Humidity TestDCR change $\leq \pm 10\%$, Conforming to Clear-Time characteristics -40° C,96hours.High Humidity TestDCR change $\leq \pm 10\%$, Conforming to Clear-Time characteristics 40° C,95%RH, 96hours.Thermal shockDCR change $\leq \pm 10\%$, Conforming to Clear-Time characteristics -40° C/30min,85°C/30min, 100cyclesFalling Shock TestDCR change $\leq \pm 10\%$ from 75 cm high

Electrical Specifications:

Clear-Time Characteristics:

Same as specified on the Short Form Data Sheet

Insulation Resistance after Opening:

20,000 ohms minimum when cleared with rated voltage applied. Fuse clearing under low voltage conditions may result in lower after clearing insulation resistance values. (Note: Under normal fault conditions (low or rated voltage conditions), WAYON chip fuses provide sufficient after clearing insulation resistance values for circuit protection.)

Current Carrying Capacity:

100% rated current at +25°C ambient for 4 hours minimum when evaluated per MIL-PRF-23419

Interrupt Ratings:

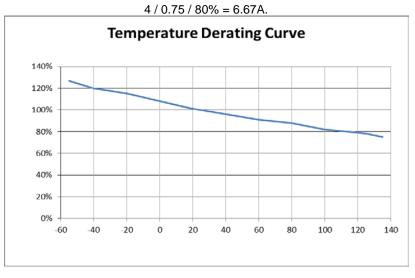
Same as specified on the Short Form Data Sheet

Fuse Selection and Temperature De-rating Guideline:

The ambient temperature affects the current carrying capacity of fuses. When a fuse is operating at a temperature higher than 25°C, the fuse shall be "de-rated".

To select a fuse from the catalog, the following rule may be followed: Catalog Fuse Current Rating = Nominal Operating Current / 0.75 / % De-rating at the maximum operating temperature.

Example: At 100°C, % De-rating is 80%. The nominal operating current is 4A. The current rating for fuse selected from the catalog shall be:



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Packaging and Storage:

Storage

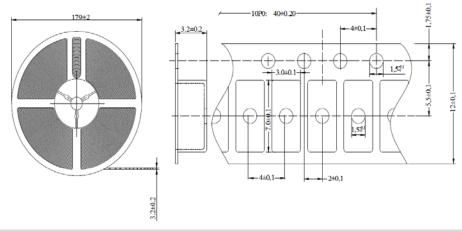
The maximum ambient temperature shall not exceed 40° C. Storage temperatures higher than 40° C could result in the deformation of packaging materials. The maximum relative humidity recommended for storage is 70%. High humidity with high temperature can accelerate the oxidation of the solder plating on the termination and reduce the solderability of the components. Sealed plastic bags with desiccant shall be used to reduce the oxidation of the termination and shall only be opened prior to use. The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present.

Packaging

WAYON's chip fuse are provided on tape-and-reel for use in pick-and-place machines or in bulk for special applications. Both tape-and-reel and bulk products are sealed in plastic bags with desiccant.

Packaging Data

1000pcs/Reel



Cautions and warnings:

1、Handling

- CHIP FUSE must not be dropped. Chip-offs must not be caused during handling of FUSEs.
- Components must not be touched with bare hands. Gloves are recommended.
- Avoid contamination of fuse surface during handling.

2、Soldering

- Use resin-type flux or non-activated flux.
- Insufficient preheating may cause ceramic cracks.
- Rapid cooling by dipping in solvent is not recommended.
- Complete removal of flux is recommended.

3、Mounting

- Electrode must not be scratched before/during/after the mounting process.
- > Contacts and housings used for assembly with fuses have to be clean before mounting.
- During operation, the fuse's surface temperature can be very high (ICL). Ensure that adjacent components are placed at a sufficient distance from the fuse to allow for proper cooling of the fuses.
- Ensure that adjacent materials are designed for operation at temperatures comparable to the surface temperature of the fuse. Be sure that surrounding parts and materials can withstand this temperature.
- Avoid contamination of fuse surface during processing.

4、Operation

- Use fuses only within the specified operating temperature range.
- Environmental conditions must not harm the fuses. Use fuses only in normal atmospheric conditions.
- Contact of chip fuses with any liquids and solvents should be prevented. It must be ensured that no water enters the chip fuse (e.g. through plug terminals). For measurement purposes (checking the specified resistance vs. temperature), the component must not be immersed in water but in suitable liquids (e.g. Galden).
- Avoid dewing and condensation.

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Notice:

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